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(12) **United States Patent**  
**Yun et al.**(10) **Patent No.:** **US 9,468,096 B2**(45) **Date of Patent:** **\*Oct. 11, 2016**(54) **EPOXY RESIN COMPOSITION, AND  
PRINTED CIRCUIT BOARD USING SAME**(71) Applicant: **LG INNOTEK CO., LTD.**, Seoul (KR)(72) Inventors: **Sungjin Yun**, Seoul (KR); **Jaе Man Park**, Seoul (KR); **Jong Heum Yoon**, Seoul (KR); **Young Ju Han**, Seoul (KR)(73) Assignee: **LG INNOTEK CO., LTD.**, Seoul (KR)

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This patent is subject to a terminal disclaimer.

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(2013.01); **C08K 3/38** (2013.01); **H05K 1/056**  
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None

See application file for complete search history.

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(57) **ABSTRACT**

According to one embodiment of the present invention, an epoxy resin composition comprises an epoxy compound, a curing agent, and an inorganic filler, wherein the inorganic filler includes boron nitride (BN).

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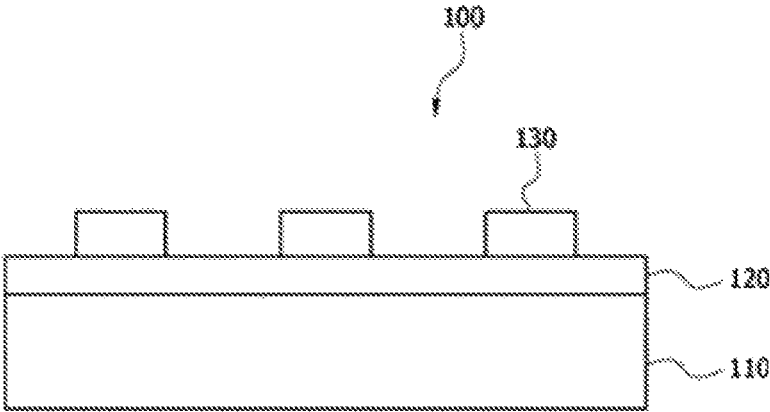
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# **EPOXY RESIN COMPOSITION, AND PRINTED CIRCUIT BOARD USING SAME**

## **CROSS-REFERENCE TO RELATED PATENT APPLICATIONS**

This application is a U.S. National Stage Application under 35 U.S.C. §371 of PCT Application No. PCT/KR2013/011314, filed Dec. 6, 2013, which claims priority to Korean Patent Application No. 10-2012-0144786, filed Dec. 12, 2012, whose entire disclosures are incorporated herein by reference.

## **TECHNICAL FIELD**

The present invention relates to an epoxy resin composition, and more particularly, to an epoxy resin composition and a printed circuit board including an insulating layer formed of the epoxy resin composition.

## **BACKGROUND ART**

A printed circuit board includes a circuit pattern formed on an insulating layer, and thus a variety of electronic parts may be mounted on the printed circuit board.

For example, the electronic parts mounted on the printed circuit board may be heating elements. Heat emitted by the heating elements may degrade the performance of the printed circuit board. With the realization of high integration and higher capacity of electronic parts, there is an increasing concern about heat dissipation problems of printed circuit boards.

To improve the heat dissipation performance, a heat dissipation sheet having a foam structure formed by a plurality of cells is proposed (Korean Unexamined Patent Application Publication No. 2004-0039090). The inside of the foam structure is filled with an inorganic filler having good thermal conductivity. Such a heat dissipation sheet is attached to a heating element to perform a thermal conduction function.

However, since the foam structure has excellent thermal insulation performance, there is a limit to the thermal conduction function of a heat dissipation sheet having the foam structure. Therefore, a method of enhancing a thermal conduction effect by minimizing pores is required.

## **DISCLOSURE**

### **Technical Problem**

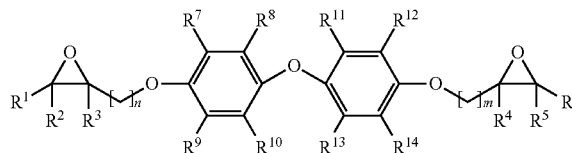
To solve the above problems, one aspect of the present invention provides an epoxy resin composition, and a printed circuit board using the same.

### **Technical Solution**

According to an aspect of the present invention, there is provided an epoxy resin composition which includes an epoxy compound represented by the following Formula 1, a curing agent, and an inorganic filler, wherein the inorganic filler includes boron nitride (BN).

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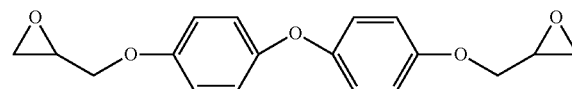
[Formula 1]



In Formula 1, R<sup>1</sup> to R<sup>14</sup> may each independently be selected from the group consisting of H, Cl, Br, F, a C<sub>1</sub>-C<sub>3</sub> alkyl, a C<sub>2</sub>-C<sub>3</sub> alkene, and a C<sub>2</sub>-C<sub>3</sub> alkyne, and m and n may each be 1, 2 or 3.

The epoxy compound may include an epoxy compound represented by the following Formula 2, and the curing agent may include diaminodiphenyl sulfone.

[Formula 2]



The inorganic filler may further include aluminum oxide. The boron nitride may be included at a content of 5 to 60 parts by weight, based on 100 parts by weight of the aluminum oxide.

According to another aspect of the present invention, there is provided a printed circuit board which includes a metal plate, an insulating layer formed on the metal plate, and a circuit pattern formed on the insulating layer, wherein the insulating layer is made of the epoxy resin composition according to one exemplary embodiment of the present invention.

## **Advantageous Effects**

According to exemplary embodiments of the present invention, an epoxy resin composition can be obtained. When the epoxy resin composition is used, an insulating layer having high thermal conductivity can be obtained, and reliability and heat dissipation performance of the printed circuit board can be improved.

## **DESCRIPTION OF DRAWINGS**

FIG. 1 is a cross-sectional view of a printed circuit board according to one exemplary embodiment of the present invention.

## **BEST MODE**

The present invention may be modified in various forms and have various embodiments, and thus particular embodiments thereof will be illustrated in the accompanying drawings and described in the detailed description. However, it should be understood that the description set forth herein is not intended to limit the present invention, and encompasses all modifications, equivalents, and substitutions that do not depart from the spirit and scope of the present invention.

Although the terms encompassing ordinal numbers such as first, second, etc. may be used to describe various elements, these elements are not limited by these terms. These terms are only used for the purpose of distinguishing one element from another. For example, a first element could

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be termed a second element, and, similarly, a second element could be termed a first element without departing from the scope of the present invention. The term "and/or" includes any and all combinations of a plurality of associated listed items.

The terminology provided herein is merely used for the purpose of describing particular embodiments, and is not intended to be limiting of exemplary embodiments of the present invention. The singular forms "a," "an" and "the" are intended to include the plural forms as well, unless the context clearly indicates otherwise. It should be understood that the terms "comprises," "comprising," "includes" and/or "including," when used herein, specify the presence of stated features, integers, steps, operations, elements, components and/or combinations thereof, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components and/or combinations thereof.

Unless defined otherwise, all the terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which the present invention belongs. It will be further understood that the terms, such as those defined in commonly used dictionaries, should be interpreted as having meanings that are consistent with their meanings in the context of the relevant art, and will not be interpreted in an idealized or overly formal sense unless expressly defined otherwise herein.

It will be understood that when it is assumed that a part such as a layer, film, region, or board is disposed "on" another part, it can be directly disposed on the other part or intervening parts may also be present therebetween. On the other hand, it will be understood that when it is assumed that a part such as a layer, film, region, or board is "directly disposed on" another part, no intervening parts may be present therebetween.

Hereinafter, exemplary embodiments of the present invention will be described in detail with reference to the accompanying drawings. Regardless of reference numerals, like numbers refer to like elements throughout the description of the figures, and the description of the same elements will be not reiterated.

In this specification, the term "% by weight(s)" may be replaced with "part(s) by weight."

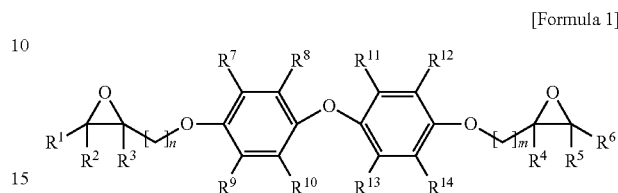
According to one aspect of the present invention, there is provided an epoxy resin composition which includes an epoxy resin having a mesogenic structure, a curing agent, and an inorganic filler, wherein boron nitride (BN) is used as the inorganic filler. Here, mesogen is a fundamental unit of a liquid crystal, and includes a rigid structure. For example, the mesogen may include a rigid structure like biphenyl, phenyl benzoate, naphthalene, etc.

The epoxy resin composition according to one exemplary embodiment of the present invention may include the epoxy compound at a content of 3% by weight to 40% by weight, preferably 5% by weight to 20% by weight, based on the total weight of the epoxy resin composition. When the epoxy compound is included at a content of 3% by weight or less based on the total weight of the epoxy resin composition, an adhesive property may be degraded. When the epoxy compound is included at a content of 40% by weight or more based on the total weight of the epoxy resin composition, it may be difficult to adjust the thickness. In this case, the epoxy resin composition may include a crystalline epoxy compound at a content of 3% by weight or more, preferably 5% by weight or more, based on the total weight of the epoxy resin composition. When the crystalline epoxy com-

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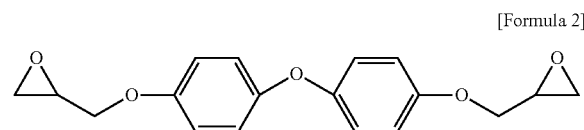
pound is included at a content of less than 3% by weight based on the total weight of the epoxy resin composition, the epoxy resin composition may not be crystallized, and thus a thermal conduction effect may be reduced.

Here, the crystalline epoxy compound may be a mesogenic compound represented by the following Formula 1.



In Formula 1, R<sup>1</sup> to R<sup>14</sup> may each independently be selected from the group consisting of H, Cl, Br, F, a C<sub>1</sub>-C<sub>3</sub> alkyl, a C<sub>2</sub>-C<sub>3</sub> alkene, and a C<sub>2</sub>-C<sub>3</sub> alkyne, and m and n may each be 1, 2 or 3.

The crystalline epoxy compound may also be represented by the following Formula 2.



The epoxy equivalent weight of the epoxy compound (hereinafter referred to as 4,4'-biphenolether diglycidyl ether) of Formula 2 may be in a range of 120 to 300, preferably 150 to 200. For the physical properties of the epoxy compound of Formula 2, the epoxy compound had a melting point of 158° C., and the <sup>1</sup>H NMR (CDCl<sub>3</sub>-d<sub>6</sub>, ppm) results are as below: δ=8.58 (s, 2H), δ=8.17-8.19 (d, 4H), δ=7.99-8.01 (d, 4H), δ=7.33 (s, 4H), δ=4.69-4.72 (d, 1H), δ=4.18-4.22 (m, 1H), δ=3.36-3.40 (m, 1H), δ=2.92-2.94 (m, 1H) and δ=2.74-2.77 (m, 1H). The melting point was measured at a heating rate of 10° C./min using a differential scanning calorimetry device (DSC Q100 commercially available from TA Instruments Ltd.). The NMR measurement was performed using H-NMR after the epoxy compound is dissolved in CDCl<sub>3</sub>-d<sub>6</sub>.

The epoxy compound of Formula 2 is crystalline at room temperature. The expression of crystallinity may be confirmed using the endothermic peaks of crystals in differential scanning calorimetric analysis. In this case, the endothermic peak may be shown as a plurality of peaks or broad peaks, the lowest temperature of the endothermic peak may be greater than or equal to 60° C., preferably 70° C., and the highest temperature of the endothermic peak may be less than or equal to 120° C., preferably 100° C.

Meanwhile, the epoxy resin composition may further include another typical amorphous epoxy compound containing two or more epoxy groups in the molecule in addition to the crystalline epoxy compound of Formula 1 or 2. When the amorphous epoxy compound is further included in addition to the crystalline epoxy compound, room-temperature stability may be improved.

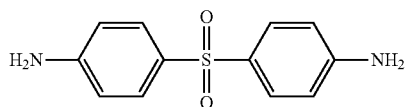
The amorphous epoxy compound may, for example, include at least one selected from the group consisting of bisphenol A, bisphenol F, 3,3',5,5'-tetramethyl-4,4'-dihydroxydiphenyl methane, 4,4'-dihydroxydiphenyl sulfone, 4,4'-dihydroxydiphenyl sulfide, 4,4'-dihydroxydiphenyl

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ketone, fluorene bisphenol, 4,4'-biphenol-3,3',5,5'-tetramethyl-4,4'-dihydroxybiphenyl, 2,2'-biphenol, resorcinol, catechol, t-butylcatechol, hydroquinone, t-butylhydroquinone, 1,2-dihydroxynaphthalene, 1,3-dihydroxynaphthalene, 1,4-dihydroxynaphthalene, 1,5-dihydroxynaphthalene, 1,6-dihydroxynaphthalene, 1,7-dihydroxynaphthalene, 1,8-dihydroxynaphthalene, 2,3-dihydroxynaphthalene, 2,4-dihydroxynaphthalene, 2,5-dihydroxynaphthalene, 2,6-dihydroxynaphthalene, 2,7-dihydroxynaphthalene, 2,8-dihydroxynaphthalene, an allylated or polyallylated compound of the dihydroxynaphthalene, a divalent phenol such as allylated bisphenol A, allylated bisphenol F, or allylated phenol novolac, or a trivalent or more phenol such as phenol novolac, bisphenol A novolac, o-cresol novolac, m-cresol novolac, p-cresol novolac, xlenol novolac, poly-p-hydroxystyrene, tris-(4-hydroxyphenyl)methane, 1,1,2,2-tetrakis(4-hydroxyphenyl)ethane, phloroglucinol, pyrogallol, t-butylpyrogallol, allylated pyrogallol, polyallylated pyrogallol, 1,2,4-benzenetriol, 2,3,4-trihydroxybenzophenone, a phenol aralkyl resin, a naphthol aralkyl resin, or a dicyclopentadiene-based resin, a glycidyl-esterified compound derived from a halogenated bisphenol such tetrabromobisphenol A, and a mixture thereof.

The resin composition according to one exemplary embodiment of the present invention may include the curing agent at a content of 0.5% by weight to 30% by weight, preferably 0.5% by weight to 5% by weight, based on the total weight of the resin composition. When the curing agent is included at a content of 0.5% by weight or less based on the total weight of the resin composition, an adhesive property may be degraded. On the other hand, when the curing agent is included at a content of 30% by weight or more based on the total weight of the resin composition, it may be difficult to adjust the thickness. The curing agent included in the resin composition may, for example, be an amine-based curing agent. For example, the amine-based curing agent may be 4,4'-diaminodiphenyl sulfone represented by the following Formula 3. The curing agent of Formula 3 may react with the epoxy resin of Formula 2 to improve thermal stability of the epoxy resin composition.

[Formula 3]



The epoxy resin composition may further include at least one selected from the group consisting of a phenolic curing agent, an amine-based curing agent, and an acid anhydride-based curing agent.

For example, the phenolic curing agent may include at least one selected from the group consisting of bisphenol A, bisphenol F, 4,4'-dihydroxydiphenyl methane, 4,4'-dihydroxydiphenyl ether, 1,4-bis(4-hydroxyphenoxy)benzene, 1,3-bis(4-hydroxyphenoxy)benzene, 4,4'-dihydroxydiphenyl sulfide, 4,4'-dihydroxydiphenyl ketone, 4,4'-dihydroxydiphenyl sulfone, 4,4'-dihydroxybiphenyl, 2,2'-dihydroxybiphenyl, 10-(2,5-dihydroxyphenyl)-10H-9-oxa-10-phosphaphenanthrene-10-oxide, phenol novolac, bisphenol A novolac, o-cresol novolac, m-cresol novolac, p-cresol novolac, xlenol novolac, poly-p-hydroxystyrene, hydroquinone, resorcinol, catechol, t-butylcatechol, t-butylhydroquinone, phloroglucinol, pyrogallol, t-butylpyrogallol, allylated pyrogallol, polyallylated pyrogallol, 1,2,4-benzenetriol, 2,3,

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4-trihydroxybenzophenone, 1,2-dihydroxynaphthalene, 1,3-dihydroxynaphthalene, 1,4-dihydroxynaphthalene, 1,5-dihydroxynaphthalene, 1,6-dihydroxynaphthalene, 1,7-dihydroxynaphthalene, 1,8-dihydroxynaphthalene, 2,3-dihydroxynaphthalene, 2,4-dihydroxynaphthalene, 2,5-dihydroxynaphthalene, 2,6-dihydroxynaphthalene, 2,7-dihydroxynaphthalene, 2,8-dihydroxynaphthalene, an allylated or polyallylated compound of the dihydroxynaphthalene, allylated bisphenol A, allylated bisphenol F, allylated phenol novolac, allylated pyrogallol, and a mixture thereof.

For example, the amine-based curing agent may include an aliphatic amine, a polyether polyamine, an alicyclic amine, an aromatic amine, etc. The aliphatic amine may include at least one selected from the group consisting of ethylenediamine, 1,3-diaminopropane, 1,4-diaminopropane, hexamethylenediamine, 2,5-dimethylhexamethylenediamine, trimethylhexamethylenediamine, diethylenetriamine, iminobis propylamine, bis(hexamethylene)triamine, triethylenetetramine, tetraethylenepentamine, pentaethylenhexamine, N-hydroxyethyl ethylenediamine, tetra(hydroxyethyl)ethylenediamine, etc. The polyether polyamine may include at least one selected from the group consisting of triethylene glycol diamine, tetraethylene glycol diamine, diethylene glycol bis(propylamine), polyoxypropylene diamine, a polyoxypropylene triamine, and a mixture thereof. The alicyclic amine may include at least one selected from the group consisting of isophorone diamine, methacene diamine, N-aminoethylpiperazine, bis(4-amino-3-methyldicyclohexyl)methane, bis(aminomethyl)cyclohexane, 3,9-bis(3-aminopropyl)-2,4,8,10-tetraoxaspiro(5,5)undecane, norbornene diamine, etc. The aromatic amine may include at least one selected from the group consisting of tetrachloro-p-xylenediamine, m-xylenediamine, p-xylenediamine, m-phenylenediamine, o-phenylenediamine, p-phenylenediamine, 2,4-diaminoanisole, 2,4-toluenediamine, 2,4-diaminodiphenylmethane, 4,4'-diaminodiphenylmethane, 4,4'-diamino-1,2-diphenylethane, 2,4-diaminodiphenylsulfone, m-aminophenol, m-aminobenzylamine, benzyl dimethylamine, 2-dimethylaminomethylphenol, triethanolamine, methylbenzylamine,  $\alpha$ -(m-aminophenyl)ethylamine,  $\alpha$ -(p-aminophenyl)ethylamine, diaminodiethyldimethyldiphenylmethane,  $\alpha,\alpha'$ -bis(4-aminophenyl)-p-diisopropylbenzene, and a mixture thereof.

For example, the acid anhydride-based curing agent may include at least one selected from the group consisting of a dodecenyl succinic anhydride, a polyadipic anhydride, a polyazelaic anhydride, a polysebacic anhydride, a poly(ethyl octadecanoic diacid) anhydride, a poly(phenyl hexadecanoic diacid) anhydride, a methyltetrahydrophthalic anhydride, a methylhexahydrophthalic anhydride, a hexahydrophthalic anhydride, a methyl himic anhydride, a tetrahydrophthalic anhydride, a trialkyl tetrahydrophthalic anhydride, a methylcyclohexene dicarboxylic anhydride, a methylcyclohexene tetracarboxylic anhydride, a phthalic anhydride, a trimellitic anhydride, a pyromellitic anhydride, a benzophenone tetracarboxylic anhydride, ethylene glycol bistrimellitate, a chlorendic anhydride, a nadic anhydride, a methyl nadic anhydride, a 5-(2,5-dioxotetrahydro-3-furanyl)-3-methyl-3-cyclohexane-1,2-dicarboxylic anhydride, a 3,4-dicarboxy-1,2,3,4-tetrahydro-1-naphthalene succinic dianhydride, a 1-methyl-dicarboxy-1,2,3,4-tetrahydro-1-naphthalene succinic dianhydride, and a mixture thereof.

The epoxy resin composition may further include a curing accelerator.

The epoxy resin composition according to one exemplary embodiment of the present invention may include the inor-

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ganic filler at a content of 30% by weight to 96.5% by weight, preferably 40% by weight to 96.5% by weight, based on the total weight of the epoxy resin composition. When the inorganic filler is included at a content of less than 30% by weight, high thermal conductivity, low thermal expansibility, and high-temperature thermal resistance of the epoxy resin composition may not be ensured. The high thermal conductivity, low thermal expansibility and high-temperature thermal resistance are improved as the inorganic filler is added at an increasing amount. The high thermal conductivity, low thermal expansibility and high-temperature thermal resistance are not improved according to the volume fraction of the inorganic filler, but start to be dramatically improved when the inorganic filler is added at a certain amount. However, when the inorganic filler is included at a content of greater than 96.5% by weight, formability is deteriorated due to an increase in viscosity.

The inorganic filler includes boron nitride (BN). Boron nitride has very excellent thermal conduction performance. Therefore, when boron nitride is used as the inorganic filler, high thermal conductivity may be realized.

Meanwhile, the inorganic filler may further include aluminum oxide ( $\text{Al}_2\text{O}_3$ ). When boron nitride and aluminum oxide are used together as the inorganic filler, the boron nitride may be present at a content of 5 to 60 parts by weight, preferably 10 to 55 parts by weight, and more preferably 14 to 50 parts by weight, based on 100 parts by weight of the aluminum oxide. When the boron nitride is included at a content of less than 5 parts by weight based on 100 parts by weight of the alumina, it is difficult to realize a desired level of thermal conductivity. On the other hand, when the boron nitride is included at a content of greater than 60 parts by weight based on 100 parts by weight of the alumina, formability is deteriorated due to an increase in viscosity.

Meanwhile, the epoxy resin composition according to one exemplary embodiment of the present invention may further include an additive at a content of 0.1% by weight to 2% by weight, preferably 0.5% by weight to 1.5% by weight, based on the total weight of the epoxy resin composition. For example, the additive may be phenoxy, or a hyperbranched polyester. When the additive is added at a content of less than 0.1% by weight, it is difficult to realize desired properties (for example, adhesivity). On the other hand, when the additive is added at a content of greater than 2% by weight, formability is deteriorated due to an increase in viscosity.

A prepreg may be prepared by coating or impregnating a fiber base or a glass base with the epoxy resin composition according to one exemplary embodiment of the present invention and semi-curing the epoxy resin composition by heating.

The epoxy resin composition according to one exemplary embodiment of the present invention may be applied to printed circuit boards. FIG. 1 is a cross-sectional view of a printed circuit board according to one exemplary embodiment of the present invention.

Referring to FIG. 1, the printed circuit board 100 includes a metal plate 110, an insulating layer 120, and a circuit pattern 130.

The metal plate 110 may be made of at least one selected from the group consisting of copper, aluminum, nickel, gold, platinum, and an alloy thereof.

The insulating layer 120 made of the epoxy resin composition according to one exemplary embodiment of the present invention is formed on the metal plate 110.

The circuit pattern 130 is formed on the insulating layer 120.

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When the epoxy resin composition according to one exemplary embodiment of the present invention is used for the insulating layer, the printed circuit board having excellent heat dissipation performance may be obtained.

Hereinafter, the present invention will be described in further detail in conjunction with Examples and Comparative Examples.

#### Example 1

10% by weight of the crystalline epoxy compound of Formula 2, and 86% by weight of boron nitride were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 3% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Example 2

16% by weight of the crystalline epoxy compound of Formula 2, and 80% by weight of boron nitride were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 3% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Example 3

10% by weight of the crystalline epoxy compound of Formula 2, 75.25% by weight of aluminum oxide, and 10.75% by weight of boron nitride were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 3% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Example 4

10% by weight of the crystalline epoxy compound of Formula 2, 76.5% by weight of aluminum oxide, and 9.5% by weight of boron nitride were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 3% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Example 5

10% by weight of the crystalline epoxy compound of Formula 2, 77.4% by weight of aluminum oxide, and 8.6% by weight of boron nitride were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 3% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the

mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Comparative Example 1

9% by weight of the crystalline epoxy compound of Formula 2, and 88% by weight of aluminum oxide were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 2% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Comparative Example 2

7% by weight of the crystalline epoxy compound of Formula 2, and 90% by weight of aluminum oxide were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 2% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

#### Comparative Example 3

5% by weight of the crystalline epoxy compound of Formula 2, and 92% by weight of aluminum oxide were stirred at room temperature for 5 to 6 minutes at a rotary speed of 2,000 rpm, and 2% by weight of 4,4'-diaminodiphenyl sulfone, and 1% by weight of a hyperbranched polyester were further added to the resulting mixture. Thereafter, copper was coated with the mixture using a thin-film coating machine until the film thickness reached 85  $\mu\text{m}$  to 100  $\mu\text{m}$ . The coated sample was cured using a hot press.

Thermal conductivity of the epoxy resin compositions of Example 1 to 5 and Comparative Example 1 to 3 was measured by means of a transient hot-wire method using a thermal conductivity meter (LFA447 commercially available from Netzsch-Gerätebau GmbH). The measured results are listed in Table 1.

TABLE 1

Experiment No.	Thermal conductivity (W/m · K)
Example 1	5.42
Example 2	7.8
Example 3	8.6
Example 4	7.5
Example 5	7.43
Comparative Example 1	3.46
Comparative Example 2	3.29
Comparative Example 3	3.29

As listed in Table 1, it could be seen that the epoxy resin compositions, which included the crystalline epoxy compound of Formula 2, 4,4'-diaminodiphenyl sulfone, and boron nitride (see Examples 1 and 2), had higher thermal conductivity than the epoxy resin compositions which included the crystalline epoxy compound of Formula 2, 4,4'-diaminodiphenyl sulfone, and aluminum oxide (see Comparative Examples 1 to 3). Also, it could be seen that the epoxy resin composition including the crystalline epoxy compound of Formula 2, 4,4'-diaminodiphenyl sulfone, alu-

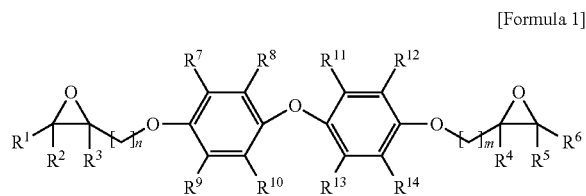
minum oxide, and boron nitride had higher thermal conductivity than the epoxy resin composition including only boron nitride as the inorganic filler, or the epoxy resin composition including only aluminum oxide as the inorganic filler.

Further, it could be seen that, when both aluminum oxide and boron nitride were included as the inorganic filler, the resin composition including boron nitride at a content of 14 parts by weight based on 100 parts by weight of the aluminum oxide as in Example 3 had higher thermal conductivity than the resin composition including boron nitride at a content of 11 to 13 parts by weight based on 100 parts by weight of the aluminum oxide as in Examples 4 and 5.

Although the preferred embodiments of the present invention have been shown and described in detail, it would be appreciated by those skilled in the art that modifications and changes may be made in these embodiments without departing from the scope of the invention, the scope of which is defined in the claims and their equivalents.

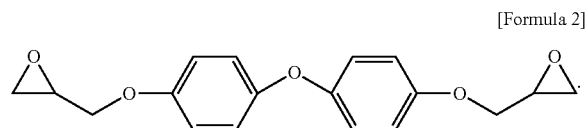
The invention claimed is:

1. An epoxy resin composition comprising:  
an epoxy compound represented by the following Formula 1;  
a curing agent comprising diaminodiphenyl sulfone; and  
an inorganic filler, wherein the inorganic filler comprises boron nitride (BN) and aluminum oxide,  
wherein the boron nitride is included at a content of 5 to 60 parts by weight, based on 100 parts by weight of the aluminum oxide:



wherein each of  $R^1$  to  $R^{14}$  is independently selected from the group consisting of H, Cl, Br, F, a  $C_1$ - $C_3$  alkyl, a  $C_2$ - $C_3$  alkene, and a  $C_2$ - $C_3$  alkyne, and each of m and n is 1, 2 or 3.

2. The epoxy resin composition of claim 1, wherein the epoxy compound comprises an epoxy compound represented by the following Formula 2:



3. The epoxy resin composition of claim 1, wherein the boron nitride is included at a content of 10 to 55 parts by weight, based on 100 parts by weight of the aluminum oxide.

4. The epoxy resin composition of claim 3, wherein the boron nitride is included at a content of 14 to 50 parts by weight, based on 100 parts by weight of the aluminum oxide.

5. The epoxy resin composition of claim 1, wherein each of m and n is 2 or 3.

6. The epoxy resin composition of claim 5, wherein each of m and n is 3.

7. The epoxy resin composition of claim 1, further comprising an amorphous epoxy compound.



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8. The epoxy resin composition of claim 1, further comprising at least one of phenoxy and hyperbranched polyester.

9. A printed circuit board comprising:

a metal plate;

an insulating layer formed on the metal plate; and 5

a circuit pattern formed on the insulating layer,

wherein the insulating layer is made of the epoxy resin composition defined in claim 1.

\* \* \* \* \*

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